

## N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY	PRODUCT SUMMARY				
V <sub>DS</sub> (V)	30				
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.001				
$R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$	0.0016				
I <sub>D</sub> (A)	260				
Configuration	Single				

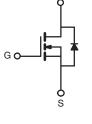
### **FEATURES**

- Halogen-free According to IEC 61249-2-21
  Definition
- TrenchFET<sup>®</sup> Power MOSFET
- Package with Low Thermal Resistance
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



FREE

### TO-220AB



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T	<sub>C</sub> = 25 °C, unles	s otherwise noted	)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V <sub>DS</sub>	30	v
Gate-Source Voltage		V <sub>GS</sub>	± 20	v
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	260	
Continuous Drain Current	T <sub>C</sub> = 125 °C	l I <sub>D</sub>	120 <sup>a</sup>	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	120	А
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	680	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	82	
Single Pulse Avalanche Energy	L = 0.1 IIIH	E <sub>AS</sub>	336	mJ
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D	375	w
	T <sub>C</sub> = 125 °C	P <sub>D</sub>	125	vv l
Operating Junction and Storage Temperature Rar	nge	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient P	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	40	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.4	0/11

#### Notes

a. Package limited.

b. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$ 

c. When mounted on 1" square PCB (FR-4 material).

d. Parametric verification ongoing.

G D S Top View



PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS}$ = 0 V, I <sub>D</sub> = 250 µA		30	-	-	v
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μΑ	1.5	2.0	2.5	v
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, $V_{GS} = \pm 20 V$	-	-	± 100	nA
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V	-	-	1	
	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ Α Ω S
		$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V, T <sub>J</sub> = 175 °C	-	-	250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	120	-	-	А
		$V_{GS} = 10 V$	I <sub>D</sub> = 30 A	-	0.001	-	Ω
Ducia Course On Otata Decistance?		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C	-	0.0023	-	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C	-	0.0028	-	
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 20 A	-	0.0016	-	
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub>	= 15 V, I <sub>D</sub> = 30 A	-	190	-	S
Dynamic <sup>b</sup>	•						
Input Capacitance	C <sub>iss</sub>			-	12484	15605	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 15 V, f = 1 MHz	-	2204	2755	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	1		-	860	1075	
Total Gate Charge <sup>c</sup>	Qg			-	179	270	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 120 \text{ A}$	-	34	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	1		-	21	-	
Gate Resistance	Rg	f = 1 MHz		0.59	1.19	1.79	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	18	27	
Rise Time <sup>c</sup>	t <sub>r</sub>	- V <sub>DD</sub> =	= 15 V, R <sub>I</sub> = 0.3 Ω	-	11	17	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 50 \text{ A},$	$V_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$	-	64	96	ns
Fall Time <sup>c</sup>	t <sub>f</sub>	]		-	11	17	
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>	·			•		
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	480	А
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> =	60 A, V <sub>GS</sub> = 0 V	-	0.81	1.5	V

Notes

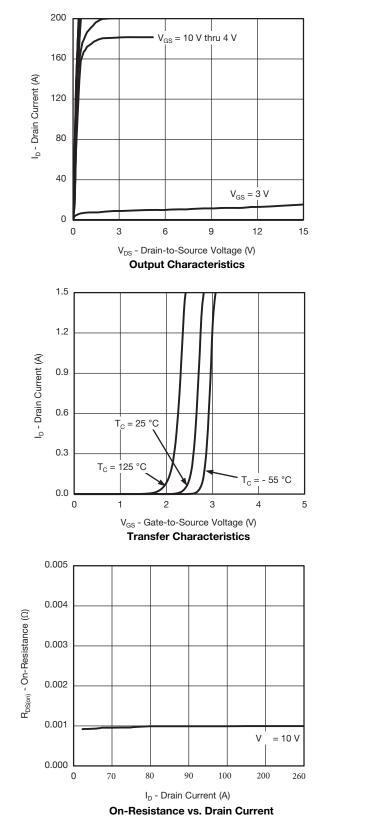
a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.

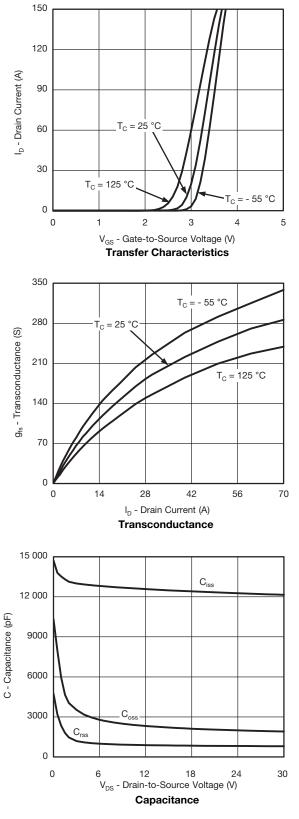
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)

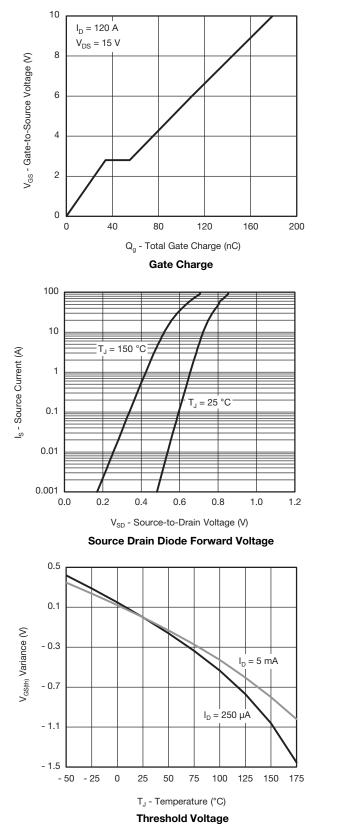




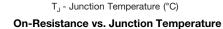
V<sub>GS</sub> = 10 V

 $V_{GS} = 4.5 V$ 

150 175



## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



2.0

1.7

1.4

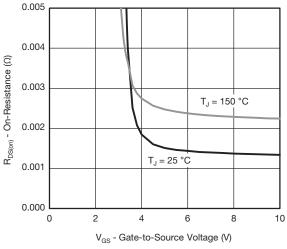
1.1

0.8

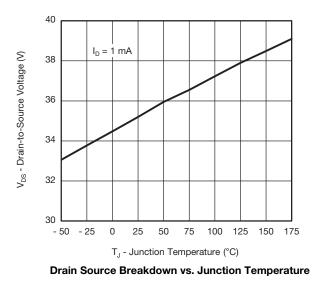
0.5

- 50 - 25 0 25 50 75 100 125

R<sub>DS(on)</sub> - On-Resistance (Normalized)  $I_D = 30 \text{ \AA}$ 

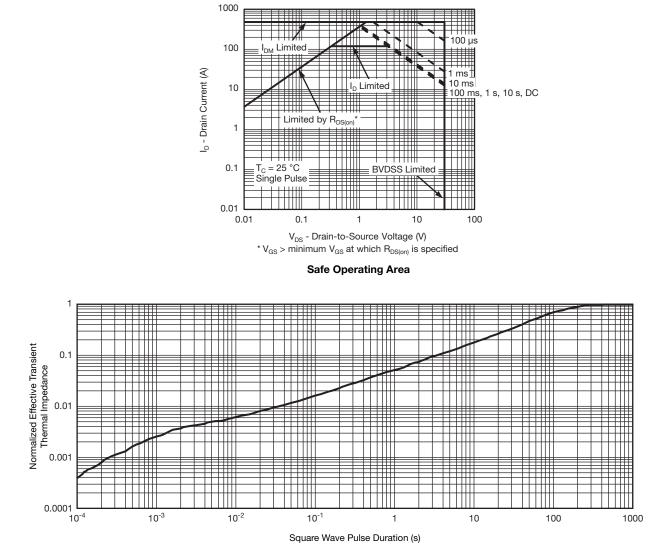








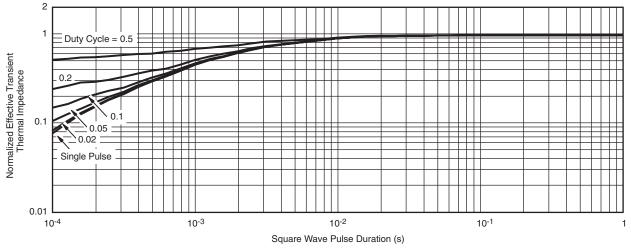
## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

• The characteristics shown in the two graphs

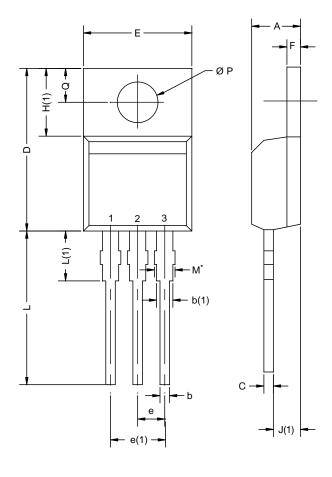
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



## **TO-220AB**



	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12- DWG: 547	0208-Rev. N, 1	08-Oct-12			

#### Notes

 $^{\star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM

## IRF1503PBF



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